

Handling, Mounting, and Operating SP High-Power Pump Lasers

This technical note provides guidelines to ensure the maximum device performance of high-power pump laser modules.

This note includes special handling requirements for S26/S27 products that differ from Planar requirements due to a slightly different butterfly package design. Also, some SP platform products operate the TEC at 45°C, requiring new techniques for safely turning on the pump module.

Actual operational configurations for pump modules and their reliability requirements depend on the customer's specific amplifier application. Therefore, JDSU does not guarantee the reliability of the module attachment or control method within customer's specific applications and can only recommend good engineering practices. The end-user must confirm the final reliability and quality of any system using a pump attachment.

Topics addressed in this application note include:

- Precautions
- Fiber Contamination and Cleaning
- Mounting
- Power Supply and Control
- TEC Control and Operation
- Appendix A: HEPCO Model 3000-2 Basic Preform Machine
- Appendix B: Copper Spacer (P/N 21141882) Drawing

Precautions

Safety

The ex-fiber-coupled power offered by JDSU pump lasers represents significant optical power in the infrared region. Be sure to follow standard safety protocol for eye and skin for Class IV IR lasers.

Electrostatic Discharge (ESD)

ESD damage to a laser diode is induced from the rapid flow of electrical charge between two bodies at different potentials, either through direct contact or through an induced electric field. ESD can cause catastrophic or latent damage and is of particular concern for the pump module's laser diode and MPD.

Latent ESD damage, which occurs when the energy of an ESD event is below the critical level required to produce a catastrophic failure, can result in defects which propagate during module deployment resulting in catastrophic failure over time.

A human body model (HBM) ESD test is used to determine the damage threshold of the pump module which are tested in accordance with GR-468-CORE section 5.22 (MIL-STD-883, method 3015.7). Refer to pump module specifications for ESD voltage limits. A number of industry specifications are available to make the work area ESD safe (for example, EIA-625, JEDEC 108-A).

Below are common recommended guidelines for preventing ESD damage to the pump modules:

- Refer to the pump module specification sheet for ESD voltage ratings.
- Use the provided shorting clips on 14-pin butterfly packages when the modules are disconnected from the operational circuit.
- Ground operators, equipment, WIP transport carts/trays, pump modules or systems, and work surface to eliminate static electricity.
- Only use confirmed ESD dissipative coatings/surface finishes on fixtures/tooling used to assemble the pump modules.
- When manipulating pump modules, use ESD protective smocks, gloves and shoes/covers, dissipative bench-top mats and ESD protective flooring or matting.
- Remove or control static generating sources to voltages below the specified maximum for safe ESD handling.
- Install air ionizers as necessary for additional environmental control.
- Use electrically grounded soldering irons for soldering the pump module to the mounting surface.
- Use electrostatic shielding containers and antistatic or dissipative carriers.

Fiber Contamination and Cleaning

Fiber contamination is a key consideration for high-power pump modules. The optical power from pump modules that is not coupled into fiber core is propagated by the fiber cladding layer a short distance from the module. Fiber contamination, especially contamination with dark color, will cause a local temperature increase as it absorbs the dissipated cladding modes.

- Wear gloves when handling fiber.
- Avoid any contamination of fiber.
- Clean a fiber if contamination occurs, being especially considerate of the first ~2' of buffer.
- No dark color contamination with an area larger than 100 μm x 100 μm is allowed within the first ~2' of buffer and should be avoided along the entire length of fiber.

Fiber cleaning materials and procedures shown below are for informational purposes only and are not meant to recommend, endorse or discredit any existing procedures. It is recommended that users evaluate any procedure or product before using it in applications where damage or failure could result. As always, safety precautions must be exercised at all times when using glass, chemicals, and lasers.

There are many materials commercially available for fiber optic cleaning. Some are marketed specifically for the fiber optic industry, while others are considered “raw materials” or generic in nature but can be used for the same purpose.

Materials discussed here include:

- Swabs
- Alcohol
- Wipes
- Adhesive
- Air

Swabs

There are applications for each type of swab. Choose the proper type of swab after experimenting with its results. Manufacturers sometimes recommend multiple uses of swabs. In some applications this may be suitable, but in others, only a single use prior to disposal is suggested.

Cotton tipped—Various sizes are available with different materials and lengths of sticks. Used dry or wetted with your choice of cleaning fluid, these are not the best in tight or unseen areas as cotton fibers may come off of the swab and adhere to connectors or become lodged in small openings.

Foam tipped—These are designed to be used with different cleaning fluids. They come in various size tips with different materials and lengths of sticks. Care should be taken to wet it properly and to dry the freshly cleaned surface.

Felt style tipped—Similar to the foam tipped, except the tip is stiffer. A hard felt-type tip softens and swells with wetting. Care should be taken to wet it properly and to dry the freshly cleaned surface.

Film—This is probably the newest style of cleaning material or fabric. This swab uses a woven film similar to the tape and reel cleaners (see Wipes). The woven material is wrapped to the end of a stick and can be used both wet and dry. The film does well in removing both particles and oils.

Alcohol

Isopropyl alcohol is the most commonly used of the alcohols in fiber optic cleaning due to its low cost and safety qualities (toxicity, flammability, environmental/disposal). Alcohol will loosen particular contaminants and aid in removing oils. It is used on swabs and wipes, by directly spraying, in soaking tubs, and in ultrasonic cleaners. The better alcohol is the higher concentration (lower water content) and 99 percent is readily available in bulk, small bottles, and pressurized spray cans with nozzle extensions.

As a general consideration, always replace the cap on bottles or the concentration will degrade because of humidity absorption and do not re-dip a wipe into the same volume of alcohol for multiple cleanings. Degradation also results when storing a bottle with little fluid and more air space for the same consideration of water absorption. If a previously opened bottle is not used in a generally short amount of storage time, it should be disposed. Spotting on a cleaned surface will indicate degradation due to moisture absorption.

Wipes

Natural fiber—Cotton wipes in various weaves are available, as well as different absorbency, thickness, and pad size.

Synthetic—Similar to the cotton wipes, but stiffer and sometimes less absorbent.

Moist—Pre-moistened wipes are available in tubs (tear off) and individually pre-packaged. The tubs should be closed after each use to keep the wipes from drying out. The individual packaged wipes are single use only. These tend to come with a lower concentration of alcohol (40 percent – 60 percent).

Dry film—Woven film similar to the tape and reel cleaners (see Wipes) is used in a card style, designed for single wipe and clean of connector tips or faces. This allows for removal of both particle and oil contamination.

Adhesive

Adhesive type cleaners are used to remove particle contamination. It is important to select an adhesive in-line with the particular application so that the adhesive itself does not create a new source of contamination or damage (whether it is the adhesive itself that adheres to a surface, or contaminant that was on the adhesive prior to cleaning causing cross-contamination or scratching and dig type damage).

Tape—A high quality common adhesive tape can be used. Use of tapes should be with reference to common MIL standards.

Pads and Sheet—Available in a pocket-sized sheet, this product has individual pads for single-use tip or end face cleaning. Keep the adhesive pads covered or contamination will result.

Air

Air is used for drying and clearing surfaces and areas of contaminants separately or after cleaning with a fluid or wipe. Open air-drying is sometimes done but can be problematic as it allows water spotting on surfaces.

All air used in fiber optics must be free of particulates and oil contaminants and should not generate increased susceptibility to ESD. Testing should be done when selecting a canned air to ensure the cleanliness, especially any residual film problems. Proper filters must be used when using house air. Canned air is most commonly used because of its portability and reliability of cleanliness.

System or house air—Pressurized air that is piped through the lab or building supplied through a compressor. Proper filters must be used and testing done to certify that the air is free of particle and oil contaminants.

Canned air—Choose a high quality canned pressurized air that, when tested on a dark glass or shiny plastic surface, leaves no residual film or oil. Do not spray from a can that has been shaken or inverted within the last half hour as some propellant may be sprayed out and possibly contaminate the surface being cleaned.

Mounting

Mounting topics include:

- Butterfly Package
- Heat Sinks
- Thermal Interface Materials
- Soldering Module Package Leads
- Fiber Fusion Splices
- Fiber Handling
- Fiber Lay Sensitivity—Polarization Effects
- Lead Bending

Butterfly Package

When mounting the SP 14-pin butterfly package, ensure that the butterfly pins are properly oriented and are not inadvertently rotated by 180°. (do not turn module by 180 degrees). See Figures 1a to 1c for the module mechanical and electrical schematics. The SP pump module has an optical height of 4.4 mm. Add a 0.8 mm-thick copper spacer (P/N 21141882, see Appendix B for drawing) when a 5.2 mm optical height is needed to match the legacy butterfly module. The copper spacer can be purchased from:

Belton Engineering Company Limited
 Unit 4-6, 12/F. Blk. B, Vigor Industrial Building, 14-20 Cheung Tat Road, Tsing Yi, N.T.,
 Hong Kong
 Tel No.: (852)24322316

The estimated cost of the spacer is about \$0.50 at volumes of 1,000 pieces and \$0.37 at volumes of 10,000 pieces. There is no notable thermal impedance change due to usage of the spacer in the pump module mounting. Follow all integrated circuit standard practices including ESD prevention when mounting the SP pump module.

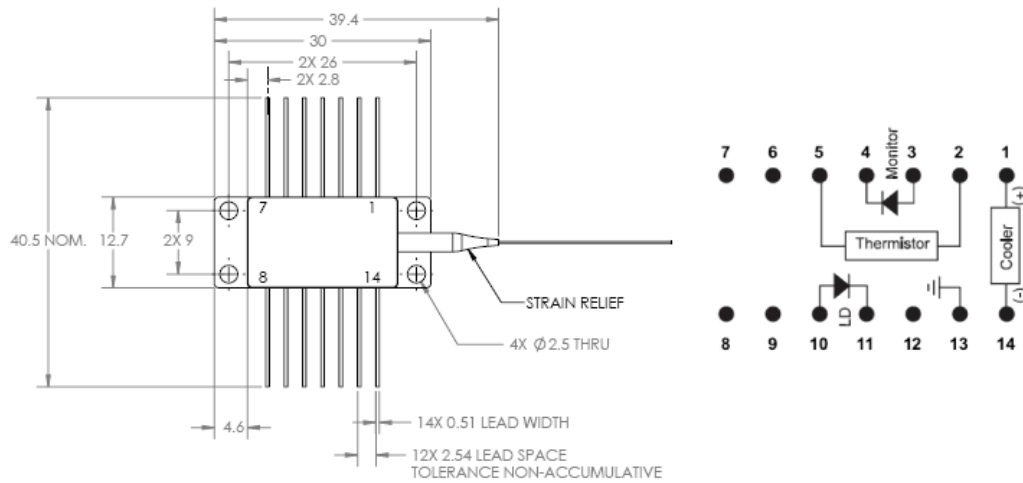


Figure 1a. Example top view and electrical schematic for a Sparta pump module

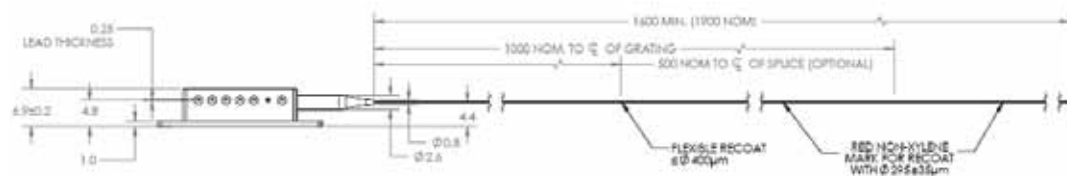


Figure 1b. Example side view and electrical schematic for a Sparta pump module without 0.8 mm spacer

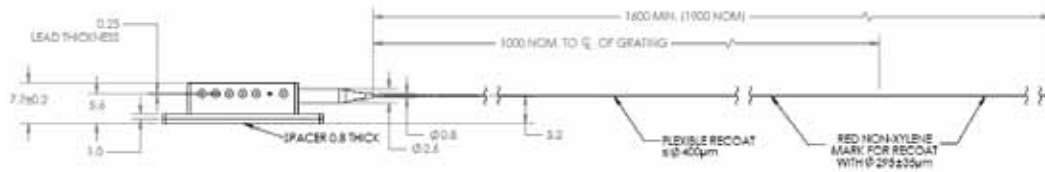


Figure 1c. Example side view and electrical schematic for a Sparta pump module with 0.8 mm spacer

Heat Sinks

The design of the receiving heat sink, intended to dissipate the heat pumped by the TEC, is crucial to the overall pump module performance and reliability. All pump modules with a TEC to control LD temperature require heat sinks and will fail catastrophically if operated without one. The goal of the heat sink design is to dissipate the heat from package base with minimized thermal resistance.

Heat sink performance is usually specified in terms of thermal resistance (Q):

$$\Theta_s = (T_s - T_a)/Q$$

where:

Θ_s = Thermal Resistance in Degrees C per Watt

T_s = Heat Sink Temperature in Degrees C

T_a = Ambient or Coolant Temperature in Degrees C

Q = Heat Input to Heat Sink in Watts

Each thermoelectric cooling application will have a unique heat sink requirement and frequently there will be various mechanical constraints that may complicate the overall design. Because each case is different, there is no single heat sink configuration suitable for all situations.

A well-designed heat sink in combination with a high-performance thermal interface material and package mounting technique should guarantee that the pump module case temperature does not exceed the maximum temperature specified for each series (refer again to the absolute maximum characteristics). Failure to keep a package base below the specified maximum temperature will lead the pump module overheating and result in module damage.

Important note: Mount the butterfly pump module on a heat sink with flatness of 50 microns or less over the entire mating surface.

The S26/S27 Series incorporates glass feedthroughs that are vulnerable to the mechanical stress that will be transmitted through the package when the base is not bolted to a flat surface meeting these specification limits.

The following general heat sink guidelines are recommended:

- Mount the pump module on a heat sink with a surface finish of 0.8 microns or less.
- The heat sink should be designed to handle at least maximum module heat dissipation through the life of the product. For total module power dissipation refer to the module specifications. Maximum module heat dissipation is approximately equal to total module power consumption (laser diode and TEC) minus the ex-fiber optical power.
- Design a heat sink that is capable of keeping the pump module case temperature below the maximum rated temperature for all operating conditions. For maximum package base temperature, refer to the pump module specification.

Thermal Interface Materials

Ideally, thermally conductive materials are used as an interface between a pump module and the heat sink to account for any flatness/smoothness discrepancies between the two parts. Suitable thermally conductive materials include phase change materials, greases, thermal compounds, elastomers, and adhesive films. All are designed to conform to surface irregularities, thereby eliminating air voids to improve heat flow between thermal interfaces.

Use thermal grease to minimize thermal resistance. If semi-rigid thermal-interface materials (for example, phase-change material or thermal pad) are used, the thermal-interface material must cover the entire base plate including the bolt-hole area to avoid bending the base during bolt down.

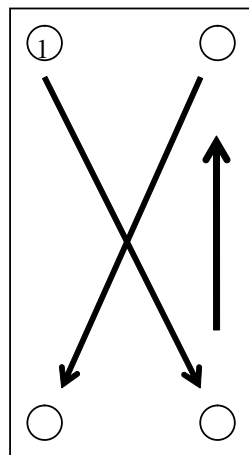
The specific choice and implementation of a thermal interface material depends on the customer's specific application and reliability considerations.

Failure to follow proper pump module mounting procedures to a properly prepared heat sink can result in high thermal resistances and module warpage, both of which can impact performance and may lead to catastrophic failure.

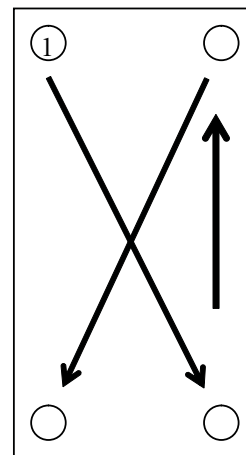
Important note: Bolt down the pump module to the heat sink in an X-style fashion with the initial torque set to 0.75 in-lb and a final X-style bolt-down at 1.5 in-lb.

The S26/S27 Series incorporates glass feedthroughs that are vulnerable to the mechanical stress that will be transmitted through the package when the base is not bolted to a flat surface meeting these specification limits.

- Use a thermal interface material with a thickness sufficient to compensate for a maximum non-planarity of 100 microns between the pump module base and the heat sink mounting surface.
- **Ensure that the thermal interface material follows the outline of the base including the four mounting screws.** If the mounting hole area is excluded, high stress may crack glass feedthroughs.
- Use a thermal interface material with a thermal conductivity of 3 W/mK or better.
- Prevent contaminating the pump module's fiber strain relief (boot) and fiber buffer with any thermal interface materials.
- Follow an X-style bolt pattern when mounting the pump module (refer to Figure 2 below).



Initial torque to ~0.75 in.lb.



Final torque to 1.5 in.lb.

Figure 2. Bolting pattern and torque specifications for mounting a butterfly module

Soldering Module Package Leads

The pump module leads can be soldered to a mounting surface using localized solder reflow techniques. A handheld iron can be used that meets the requirements of the solder temperature dwell time, maximum temperature, and force applied at the joint area.

- Use a handheld iron with a tip small enough to achieve reflow in less than 3s to prevent module components damage.
- Do not exceed a lead temperature of 260°C during the soldering operation. The pump module base must be properly heatsunk to avoid overheating the inside components.
- Allow the module to cool down to ambient temperatures after the pump module leads are soldered to the mounting surface.
- Ensure that during any soldering operation the fiber temperature does not exceed 85°C either through exposure to the soldering iron or other hot surfaces. A fiber-coupled pump module is easily damaged if a hot solder iron touches the fiber. While this may not immediately break the fiber, it will increase loss due to local stresses, and it will compromise the physical strength of the fiber and integrity of the recoat buffer. A fiber damaged by a hot soldering iron is no longer a reliable device and should be replaced.
- Prevent fiber heating above 85°C when performing any lead-soldering operation.

Fiber Fusion Splices

Splice losses have a profound impact on the quality of system performance and long-term reliability. Pump modules spliced with a high loss dissipate more heat to the local surrounding which may cause fiber buffer temperature increase or damage to the secondary surroundings. Fiber temperature increases can lead to catastrophic damage of the fiber or to long-term reliability considerations.

Avoid splice loss greater than 0.25 dB.

Fiber Handling

Both the fiber buffer and grating section are heat sensitive as well as being susceptible to buffer damage. Care must be taken during the setup and qualification of any process used in the handling and assembly of pump modules as the buffer is readily susceptible to damage—even, for example, by coiling the fiber during product assembly and securing the coil with sections of solder or wire. This practice is commonly seen and is known to cause compression and delamination damage to the optical buffer.

Maximum storage and exposure temperatures for optical buffer are 85°C as recommended by fiber manufacturers. Exposure of the buffer to temperatures above 85°C will likely cause permanent damage to the pigtail. If temperature exposure beyond 85°C is required, it is critical to understand the risk associated with the optical fiber reliability.

The optical buffer is susceptible to damage to the buffer and the damage is typically classified under 10-40X magnifications as:

- M0: contamination of the surface of the fiber (for example by debris or epoxy)—this contamination should not be removed by solvents or mechanical force; it can be removed by gentle swabbing with a foam-tipped probe.
- M1: Delamination of the buffer from the glass fiber but no compromise in the buffer integrity and the buffer diameter remains fixed. Delamination is typically caused by compression of the optical fiber and although small sections of delamination (for example, one mm long) do not introduce reliability risks, they do imply over-handling or processing where potential damage can be incurred to the buffer.

- M2: Compression of the buffer occurs when the physical diameter of the buffer has been reduced due to a force on the fiber. This will typically appear as an indentation or ‘dent’ in the buffer and may be accompanied by delamination. A compression defect again has no breach of integrity of the buffer and presents no immediate reliability risk, but does imply a concern with regards to processing and handling the pump module.
- M3: Cracked acrylate sections of the buffer occur when damage to the buffer causes it to crack. While there may not be any evidence of directly exposed glass fiber, the buffer integrity is compromised and presents a reliability hazard. JDSU screens for this type of defect prior to module shipment due to the reliability risk it poses.
- M4: Exposed glass sections of the fiber are the highest reliability risk and pose severe reductions to the inherent proof-test strength of the optical fiber. JDSU also screens for this type of damage due to its reliability hazard.

Follow the proper procedure of fiber handling to avoid catastrophic damage in fiber in high-power pump lasers:

- Do not expose fiber to temperatures higher than 85°C.
- Always wear finger cots or gloves when handling fiber to avoid fiber contamination.
- Whenever possible, handle fiber in loops to prevent fiber damage
- Do not drag fiber over equipment.
- Avoid a fiber contact with any sharp object.
- Never use the fiber to pick up or support the weight of the pump laser. Always handle modules with two hands, one holding a package and the other handling fiber coil to avoid fiber damage or breakage.
- Do not allow kinks or knots to develop in the fiber. Carefully work out any tangles; pulling on the fiber will cause any kinks or curls to tighten and exceed the minimum bend radius.
- Do not bend a fiber with a radius smaller than specified as minimum bending radius for each specific pump module series. Refer to the module specification for a value.

Bending the fiber to a smaller than specified minimum radius can result in an increased fiber temperature due to a bend loss and subsequent optical absorption by the fiber and its buffer. Catastrophic damage of the fiber can occur due to a crack growth induced by temperature increase. In less severe bend situations, a temperature increase can lead to degradation of the coating and long-term reliability issues.

Fiber Lay Sensitivity—Polarization Effects

Wavelength stabilization of pump modules is realized by writing a slightly reflective, narrow-band fiber Bragg grating (FBG) into the module pigtail roughly one meter away from the butterfly package. The majority of the pump laser light passes through the FBG, but a small percentage (less than five percent) reflects back into the DL providing optical feedback. If the amount of reflected light is adequate, the optical feedback ensures that the laser operates only at the FBG wavelength even if the drive current or temperature varies widely.

The key to effective wavelength stabilization is maintaining adequate optical feedback into the DL cavity. The laser chip is, however, a polarized light source producing a fundamental TE-polarized lateral mode pattern. Consequently, only the TE-polarized component of the FBG feedback can

influence the diode laser. Any birefringence in the round-trip optical path from the DL to the FBG reduces the amount of reflected light providing the optical feedback. If birefringence produces a polarization rotation near 90 degrees, then there is little or no effective optical feedback and the diode laser is decoupled from the FBG.

Birefringence in the pump module pigtail must be minimized by the EDFA assembler through proper fiber handling techniques and production controls. Birefringence can arise if the pigtail is twisted during spooling, bent to too tight a radius, or if the method of securing the pigtail places any stress on the fiber or allows the fiber to move during pump laser operation. NOTE: JDSU recommends that the customer spool the pump module pigtail to a radius above the specified 16 mm minimum, taking care that axial rotation of the fiber is minimized during the process. Once spooling is complete, the pigtail must be secured in place with the proper method, ensuring a fiber-bending radius with the specified 16 mm minimum.

Following these guidelines will minimize birefringence and optimize the spectral performance of the pump module. If poor spectral performance is observed subsequent to the original spooling of the fiber, the spooling process should be repeated.

Lead Bending

If the external leads require bending into a preferred shape (for example, bending leads upwards or downwards 90° as shown in Figures 3a and 3b), the following simple and low cost lead-forming tool is recommended.

Important note: Do not apply more than 0.227 kg (8 ounces) of tensile force on the leads to prevent cracking of the lead seal to the housing. The S26/S27 Series employs glass seals that require special care since they are less robust than the ceramic feedthroughs found on the Planar Series product.

Model: HEPCO Model 3000-2 Basic Preform Machine (Appendix A). Dies are customized to desired lead shape.

Company: HEPCO, INC.

Address: 150 San Lazaro Ave., Sunnyvale, CA 94086

Contact: Mr. Bill Manfroy

Tel: (408)738-1880

Fax: (408)732-4456

email: info@hepcoblue.com

web address: www.hepcoblue.com

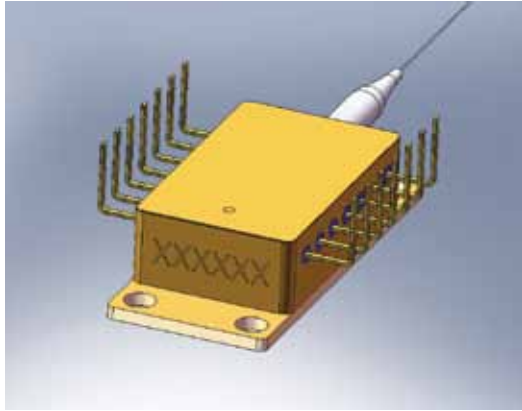


Figure 3a. Leads bent upwards 90°

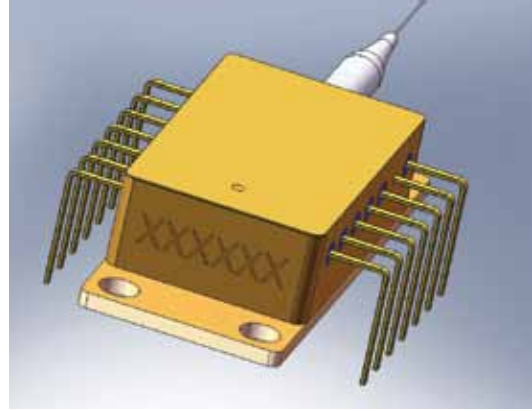


Figure 3b. Leads bent downwards 90°

Note: Care must be taken not to pull on the leads to prevent cracking of the lead seal to the housing.

Power Supply and Control

General laser diode (LD) power supply design requirements are applicable to high-power pump modules. Failure to follow these requirements may result in pump module degradation or failure. When designing or utilizing an LD or TEC power supply, designers should refer to the specified Absolute Maximum Ratings specified for each series of high-power pump lasers.

AMR Specification	LD Reverse Voltage	LD Forward Current
S26	2V	1000 mA
S27	2.5V	1200 mA
S30	2V	1400 mA

Electrical overstress (EOS) damage occurs when a pump module is subjected to voltage or current levels beyond its surge-absorbing capacity. The location and degree of damage depends on the magnitude and duration of the voltage, current, total energy, polarity, and waveform of the electrical overstress.

Power supplies and test equipment can induce EOS. Recommended guidelines for preventing EOS of pump modules include:

- Transient electrical stress to the pump module should be avoided or minimized through operational life. The maximum specified transient current time for a pump module should never be exceeded while operating a LD; refer to the absolute maximum ratings (AMR) in the pump module specifications.
- Use transient suppression for power supplies.
- Use over voltage protection for power supplies and fuses at critical locations.
- Confirm modules are mounted with the correct electrical pin configurations as specified.
- Ensure that all operational and assembly equipment is properly grounded with no loose connections (which can lead to intermittent connections).
- Always ensure the TEC controller is enabled and that the pump module is being actively cooled *prior* to turning on the laser diode controller. Allow the internal temperature of the pump module to stabilize at $25 \pm 2^\circ\text{C}$ before turning on the LD.

TEC Control and Operation

Large-capacity thermoelectric coolers (TECs) are used to control cooled pump module temperature for high power operation. Proper operational procedures for the TEC are critical for reliable performance of the modules during their lifetime. Pump module TECs typically are operated with closed-loop temperature controllers/power supply circuits. Closed-loop circuits allow maintaining internal temperatures of the pump modules at 25°C (nominally) for varying ambient temperatures (45°C for S26/S27 Series). The TEC can be switched from a cooling mode to a heating mode by reversing the direction of current flow.

Power Supply

The pump module TEC operates from a DC power source. An important criterion for reliable module operation is to use a filtered DC current. DC ripple affects the TEC performance and, as the result, subsequent module performance and lifetime.

The TEC power supply should be limited to the absolute maximum TEC current as specified for each model of pump module. The TEC can run at the absolute maximum TEC current for a very limited duration without impacting module reliability. The pump TEC is more efficient when it operates in heating mode. Therefore, the forward and reverse TEC current absolute maximum ratings (TEC I AMR) are not the same absolute value. Using symmetric current limits that exceed the recommended TEC I AMR values can compromise the reliability of the pumps and lead to a thermal overshoot.

When the pump module is first turned on there will be a transient current supplied to the TEC as it stabilizes via the feedback circuit. Note that the absolute maximum TEC current is different from the maximum operating current. The maximum operating current is the current at which a TEC can operate safely up to 25 years. The maximum operating current is specified for each series of pump modules.

Important note for S26/S27 modules operating at 45°C internal temperature: If gain and ITEC limit settings are incorrect, turn-on heating transients will damage the pump module. ITEC EOL must be limited to the maximum EOL value for the specific product rating.

In summary:

- **Limit the maximum TEC current to less/equal to the EOL current (ITEC EOL) to avoid TEC thermal runaway, especially when the internal temperature is set to 45°C.**

Product Family	TEC Current (Minimum)	TEC Current (Maximum)
S26, S27	-0.75 A	1.5 A
S30	-1.00 A	4.00 A

- Limit TEC power supply ripple factor to less than 10 percent.
- Do not operate the TEC at its rated maximum current except as transient applied current during module start-up
- Set asymmetric TEC control limits in the pump laser thermal control circuitry.
- Operate the TEC in constant temperature mode rather than in constant current mode utilizing temperature feedback from the module thermistor.

Temperature Controller

Pump module TECs operate with closed-loop temperature controller/power supply circuits. A thermistor can control the LD temperature within the pump module to the specified laser diode operating temperature for a specific product series through the specified operational ambient temperature range.

The SP “closed loop response time,” defined as the time the system takes to attain to the target temperature within $\pm 2^{\circ}\text{C}$ is approximately 1.5 to 2s for a well-tuned system. The tuning of the control system is dependent upon many factors (e.g. the PI control loop, laser diode, TEC capacity, TEC time constant, heat sink, air flow, laser diode current, case temperature, etc.).

It is important to note that if the 14-pin butterfly package thermistor leads do not have electrical contact when the package is mounted and operated, the temperature controller/power supply loop will be open. An open loop TEC will run at its maximum available power supply current and can result in permanent module damage. This situation can arise for example by placing a pump module into an active TEC powered circuit board with pins 1 and 14 on the butterfly package placed first.

- Make sure that the electrical circuit connected to the pump module has the correct orientation for mounting the 14-pin butterfly package. As the pump module is symmetrical, it is possible to connect it backwards by 180 degrees (see Figure 1 for example mechanical and electrical schematics).
- Make sure that all 14-pin butterfly leads have electrical contacts to avoid controller/power supply open circuits.
- Ensure the TEC leads are connected to the proper electrical polarity and ensure that the TEC power supply is turned off prior to mounting or un-mounting the pump module.
- Wait until the internal temperature has stabilized to $25 \pm 2^{\circ}\text{C}$ after turning the LD on before making any TEC control changes.
- Do not leave a module operating without making sure that the internal laser temperature is at $25 \pm 2^{\circ}\text{C}$.

Appendix A: HEPCO Model 3000-2 Basic Preform Machine



Single Machine To Trim and/or Form All These Components and More:

- | | | |
|-------------|------------|--------|
| Capacitors | Hall Cells | Triacs |
| Transistors | Resistors | LEDs |
| Flat Packs | Crystals | DIPs |
| Headers | Connectors | SIPs |

- Die Changes in Under 1 Minute / **Versatile**
- Steel Base for Extremely Long Life / **Durable**
- Large Variety of Dies Available
- Slash Labor Costs Over Hand Tool Use
- Precision Dies to Protect Components During Form
- Virtually No Operator/ **Simple to Use**
- Maintenance Free / **Accurate**
- Special Dies to Customer Specifications
- Rapid Payback / **Efficient**
- Immediate Delivery

Quality and Durability Proven by Years of Production Use

Specifications:

Power: 50-90 PSI Compressed Air	Average Production Rate: 2-Leaded = ~1,250 per Hour
Volume: 0.1 CFM Max	3-Leaded = ~900 per Hour
Size: 8" Wide x 5" High x 15" Long	
Weight: 25 Pounds	

Appendix B: Copper Spacer (P/N 21141882) Drawing

